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TL2575, TL2575HV 1-A SIMPLE STEP-DOWN SWITCHING VOLTAGE REGULATORS

SLVS638B-MAY 2006-REVISED JANUARY 2007

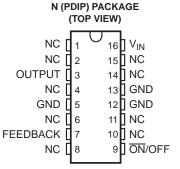
FEATURES

- Fixed 3.3-V, 5-V, 12-V, and 15-V Options With ±5% Regulation (Max) Over Line, Load, and Temperature Conditions
- Adjustable Option With a Range of 1.23 V to 37 V (57 V for HV Version) and ±4%
 Regulation (Max) Over Line, Load, and Temperature Conditions
- Specified 1-A Output Current
- Wide Input Voltage Range...4.75 V to 40 V (60 V for HV Version)
- Require Only Four External Components (Fixed Versions) and Use Readily Available Standard Inductors
- 52-kHz (Typ) Fixed-Frequency Internal Oscillator
- TTL Shutdown Capability With 50-μA (Typ) Standby Current
- High Efficiency...as High as 88% (Typ)
- Thermal Shutdown and Current-Limit Protection With Cycle-by-Cycle Current Limiting

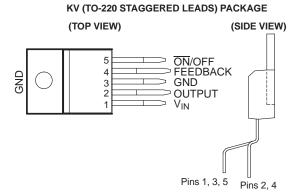
APPLICATIONS

- Simple High-Efficiency Step-Down (Buck) Regulators
- · Pre-Regulators for Linear Regulators
- On-Card Switching Regulators
- Positive-to-Negative Converters (Buck-Boost)

KTT (TO-263) PACKAGE (TOP VIEW) 5 4 FEEDBACK 3 GND 2 OUTPUT 1 V_{IN}



NC - No internal connection



DESCRIPTION/ORDERING INFORMATION

The TL2575 and TL2575HV greatly simplify the design of switching power supplies by conveniently providing all the active functions needed for a step-down (buck) switching regulator in an integrated circuit. Accepting a wide input voltage range of up to 60 V (HV version) and available in fixed output voltages of 3.3 V, 5 V, 12 V, 15 V, or an adjustable-output version, the TL2575 and TL2575HV have an integrated switch capable of delivering 1 A of load current, with excellent line and load regulation. The device also offers internal frequency compensation, a fixed-frequency oscillator, cycle-by-cycle current limiting, and thermal shutdown. In addition, a manual shutdown is available via an external $\overline{\text{ON}}/\text{OFF}$ pin.

The TL2575 and TL2575HV represent superior alternatives to popular three-terminal linear regulators. Due to their high efficiency, the devices significantly reduce the size of the heatsink and, in many cases, no heatsink is required. Optimized for use with standard series of inductors available from several different manufacturers, the TL2575 and TL2575HV greatly simplify the design of switch-mode power supplies by requiring a minimal addition of only four to six external components for operation.

The TL2575 and TL2575HV are characterized for operation over the virtual junction temperature range of -40°C to 125°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ORDERING INFORMATION⁽¹⁾ TL2575 (V_{IN(MAX)} = 40 V)

TJ	V _O (NOM)	PAC	KAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PDIP – N	Tube of 25	TL2575-33IN	TL2575-33IN
	3.3 V	TO-263 – KTT	Reel of 500	TL2575-33IKTTR	TL2575-33I
		TO-220 – KV	Tube of 50	TL2575-33IKV	TL2575-33I
		PDIP – N	Tube of 25	TL2575-05IN	TL2575-05IN
	5 V	TO-263 - KTT	Reel of 500	TL2575-05IKTTR	TL2575-05I
		TO-220 – KV	Tube of 50	TL2575-05IKV	TL2575-05I
	12 V	PDIP – N	Tube of 25	TL2575-12IN	TL2575-12IN
-40°C to 125°C		TO-263 – KTT	Reel of 500	TL2575-12IKTTR	TL2575-12I
		TO-220 – KV	Tube of 50	TL2575-12IKV	TL2575-12I
		PDIP – N	Tube of 25	TL2575-15IN	TL2575-15IN
	15 V	TO-263 – KTT	Reel of 500	TL2575-15IKTTR	TL2575-15I
		TO-220 – KV	Tube of 50	TL2575-15IKV	TL2575-15I
		PDIP – N	Tube of 25	TL2575-ADJIN	TL2575-ADJIN
	ADJ	TO-263 – KTT	Reel of 500	TL2575-ADJIKTTR	TL2575ADJI
		TO-220 – KV	Tube of 50	TL2575-ADJIKV	TL2575ADJI

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ORDERING INFORMATION⁽¹⁾ TL2575HV $(V_{IN(MAX)} = 60 \text{ V})$

T _J	V _O (NOM)	PACKAG	SE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PDIP – N	Tube of 25	TL2575HV-33IN	TL2575HV-33IN
	3.3 V	TO-263 – KTT	Reel of 500	TL2575HV-33IKTTR	2BHV-33I
		TO-220 – KV	Tube of 50	TL2575HV-33IKV	TL2575HV-33I
		PDIP – N	Tube of 25	TL2575HV-05IN	TL2575HV-05IN
	5 V	TO-263 – KTT	Reel of 500	TL2575HV-05IKTTR	2BHV-05I
		TO-220 – KV	Tube of 50	TL2575HV-05IKV	TL2575HV-05I
	12 V	PDIP – N	Tube of 25	TL2575HV-12IN	TL2575HV-12IN
-40°C to 125°C		TO-263 – KTT	Reel of 500	TL2575HV-12IKTTR	2BHV-12I
		TO-220 – KV	Tube of 50	TL2575HV-12IKV	TL2575HV-12I
		PDIP – N	Tube of 25	TL2575HV-15IN	TL2575HV-15IN
	15 V	TO-263 – KTT	Reel of 500	TL2575HV-15IKTTR	2BHV-15I
		TO-220 – KV	Tube of 50	TL2575HV-15IKV	TL2575HV-15I
		PDIP – N	Tube of 25	TL2575HV-ADJIN	TL2575HV-ADJIN
	ADJ	TO-263 – KTT	Reel of 500	TL2575HV-ADJIKTTR	2BHV-ADJI
		TO-220 – KV	Tube of 50	TL2575HV-ADJIKV	TL2575HVADJI

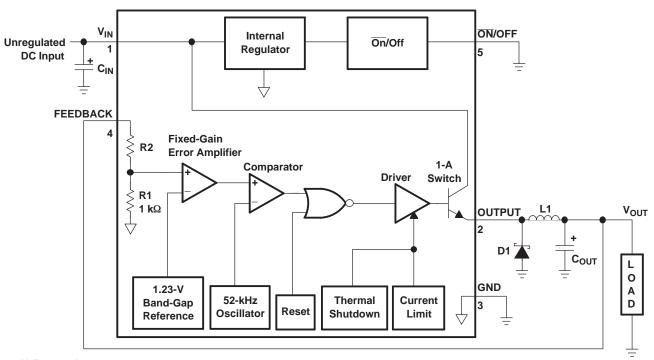
⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

⁽²⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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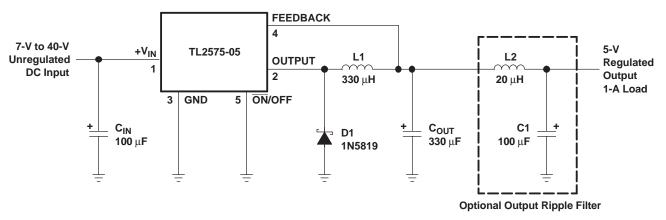
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FUNCTIONAL BLOCK DIAGRAM



3.3 V: R2 = 1.7 k Ω 5 V: R2 = 3.1 k Ω 12 V: R2 = 8.84 k Ω 15 V: R2 = 11.3 k Ω ADJ: R1 = Open, R2 = 0 Ω

A. Pin numbers are for the KTT (TO-263) package.



A. Pin numbers are for the KTT (TO-263) package.

Figure 1. Typical Application Circuit (Fixed Version)



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{IN}	TL2575HV			60	V
	Supply voltage	TL2575		42	V
	ON/OFF input voltage range		-0.3	V_{IN}	V
	Output voltage to GND (steady state)			-1	V
T_{J}	Maximum junction temperature			150	°C
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Package Thermal Data⁽¹⁾

PACKAGE	BOARD	θ_{JA}	θЈС	θ _{JP} ⁽²⁾
PDIP (N)	High K, JESD 51-7	67°C/W	57°C/W	
TO-263 (KTT)	High K, JESD 51-5	26.5°C/W	31.8°C/W	0.38°C/W
TO-220 (KV)	High K, JESD 51-5	26.5°C/W	31.8°C/W	0.38°C/W

Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 For packages with exposed thermal pads, such as QFN, PowerPADTM, or PowerFLEXTM, θ_{JP} is defined as the thermal resistance

Recommended Operating Conditions

			MIN	MAX	UNIT
V _{IN} Supply voltage	Cumply welters	TL2575HV	4.75	60	1/
	TL2575		4.75	40	V
T_{J}	Operating virtual junction temperature		-40	125	°C

between the die junction and the bottom of the exposed pad.



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TL2575 Electrical Characteristics

	DADAMETED		TEST COMPLETIONS	_	TL2575			
	PARAMETER		TEST CONDITIONS	TJ	MIN	TYP	MAX	UNIT
			V _{IN} = 12 V, I _{LOAD} = 0.2 A	25°C	3.234	3.3	3.366	
		TL2575-33	$4.75 \text{ V} \le \text{V}_{\text{IN}} \le 40 \text{ V},$	25°C	3.168	3.3	3.432	Í
			0.2 A ≤ I _{LOAD} ≤ 1 A	Full range	3.135		3.465	
			V _{IN} = 12 V, I _{LOAD} = 0.2 A	25°C	4.9	5	5.1	
		TL2575-05	8 V ≤ V _{IN} ≤ 40 V,	25°C	4.8	5	5.2	
\/	Output voltage		0.2 A ≤ I _{LOAD} ≤ 1 A	Full range	4.75		5.25	V
V _{OUT}	Output voltage		$V_{IN} = 25 \text{ V}, I_{LOAD} = 0.2 \text{ A}$	25°C	11.76	12	12.24	V
		TL2575-12	15 V ≤ V _{IN} ≤ 40 V,	25°C	11.52	12	12.48	
			0.2 A ≤ I _{LOAD} ≤ 1 A	Full range	11.4		12.6	
			V _{IN} = 30 V, I _{LOAD} = 0.2 A	25°C	14.7	15	15.3	
		TL2575-15	18 V ≤ V _{IN} ≤ 40 V,	25°C	14.4	15	15.6	
			0.2 A ≤ I _{LOAD} ≤ 1 A	Full range	14.25	15	15.75	
			V _{IN} = 12 V, V _{OUT} = 5 V, I _{LOAD} = 0.2 A	25°C	1.217	1.23	1.243	
	Feedback voltage	TL2575-ADJ	$8 \text{ V} \le \text{V}_{\text{IN}} \le 40 \text{ V}, \text{V}_{\text{OUT}} = 5 \text{ V},$	25°C	1.193	1.23	1.267	V
			0.2 A ≤ I _{LOAD} ≤ 1 A	Full range	1.18		1.28	
		TL2575-33	V _{IN} = 12 V, I _{LOAD} = 1 A			75		%
		TL2575-05	V _{IN} = 12 V, I _{LOAD} = 1 A			77		
η	Efficiency	TL2575-12	V _{IN} = 15 V, I _{LOAD} = 1 A	25°C		88		
.,		TL2575-15	V _{IN} = 18 V, I _{LOAD} = 1 A	200		88		
		TL2575-ADJ	$V_{IN} = 12 \text{ V}, V_{OUT} = 5 \text{ V}, I_{LOAD} = 1 \text{ A}$			77		
	Feedback bias curre	ont	V _{OUT} = 5 V (ADJ version only)	25°C		50	100	nA
I _{IB}	reeuback bias cum	eni	V _{OUT} = 5 V (AD3 Version only)	Full range			500	IIA
	Os sillatas fas accesas	.(1)		25°C	47	52	58	1.11=
f _o	Oscillator frequency	/ (·)		Full range	42		63	kHz
	Coturation valtage		1 (2)	25°C		0.9	1.2	V
V_{SAT}	Saturation voltage		$I_{OUT} = 1 A^{(2)}$	Full range			1.4	V
	Maximum duty cycle	e ⁽³⁾		25°C	93	98		%
	Curitoh na ala aurona	·(1)(2)		25°C	1.7	2.8	3.6	^
I _{CL}	Switch peak current	[(·/\ - /		Full range	1.3		4	Α
	Output lookogs	· ant	V _{IN} = 40 ⁽⁴⁾ , Output = 0 V	2F°C			2	A
IL	Output leakage curi	ent	$V_{IN} = 40^{(4)}$, Output = -1 V	25°C		7.5	30	mA
IQ	Quiescent current ⁽⁴)		25°C		5	10	mA
I _{STBY}	Standby quiescent	current	OFF (ON /OFF = 5 V)	25°C		50	200	μΑ

⁽¹⁾ In the event of an output short or an overload condition, self-protection features lower the oscillator frequency to ~18 kHz and the minimum duty cycle from 5% to ~2%. The resulting output voltage drops to ~40% of its nominal value, causing the average power dissipated by the IC to lower.

⁽²⁾ Output is not connected to diode, inductor, or capacitor. Output is sourcing current.

⁽³⁾ FEEDBACK is disconnected from output and connected to 0 V.

⁽⁴⁾ To force the output transistor off, FEEDBACK is disconnected from output and connected to 12 V for the adjustable, 3.3-V, and 5-V versions and to 25 V for the 12-V and 15-V versions.



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TL2575 Electrical Characteristics (continued)

PARAMETER		TEST CONDITIONS	_	TL2575			UNIT
		TEST CONDITIONS	TJ	MIN	TYP	MAX	CIVII
V	ON/OFF high-level logic	OFF (V = 0.V)	25°C	2.2	1.4		V
V _{IH}	input voltage	OFF (V _{OUT} = 0 V)	Full range	2.4			V
V	ON/OFF low-level logic	ON ()/ _ nominal voltage)	25°C		1.2	1	V
V_{IL}	input voltage	ON (V _{OUT} = nominal voltage)	Full range			0.8	V
I _{IH}	ON/OFF high-level input current	OFF (ON/OFF = 5 V)	25°C		12	30	μΑ
I _{IL}	ON/OFF low-level input current	ON $(\overline{ON}/OFF = 0 \text{ V})$	25°C		0	10	μΑ



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TL2575HV Electrical Characteristics

	242445		TEGT COMPLETIONS	_	TL2575HV			
	PARAMETER	₹	TEST CONDITIONS	T _J	MIN	TYP	MAX	UNIT
			V _{IN} = 12 V, I _{LOAD} = 0.2 A	25°C	3.234	3.3	3.366	
		TL2575HV-33	$4.75 \text{ V} \le \text{V}_{IN} \le 60 \text{ V},$	25°C	3.168	3.3	3.450	
			$0.2 \text{ A} \le I_{\text{LOAD}} \le 1 \text{ A}$	Full range	3.135		3.482	
			V _{IN} = 12 V, I _{LOAD} = 0.2 A	25°C	4.9	5	5.1	
		TL2575HV-05	8 V ≤ V _{IN} ≤ 60 V,	25°C	4.8	5	5.225	
V	Output valtage		$0.2 \text{ A} \le I_{LOAD} \le 1 \text{ A}$	Full range	4.75		5.275	V
V _{OUT}	Output voltage		V _{IN} = 25 V, I _{LOAD} = 0.2 A	25°C	11.76	12	12.24	V
		TL2575HV-12	$15 \text{ V} \le \text{V}_{IN} \le 60 \text{ V},$	25°C	11.52	12	12.54	
			$0.2 \text{ A} \le I_{LOAD} \le 1 \text{ A}$	Full range	11.4		12.66	
			$V_{IN} = 30 \text{ V}, I_{LOAD} = 0.2 \text{ A}$	25°C	14.7	15	15.3	
		TL2575HV-15	18 V ≤ V _{IN} ≤ 60 V,	25°C	14.4	15	15.68	
			$0.2 \text{ A} \le I_{LOAD} \le 1 \text{ A}$	Full range	14.25	15	15.83	
			$V_{IN} = 12 \text{ V}, V_{OUT} = 5 \text{ V}, $ $I_{LOAD} = 0.2 \text{ A}$	25°C	1.217	1.23	1.243	
	Feedback voltage	TL2575HV-ADJ	8 V ≤ V _{IN} ≤ 60 V, V _{OUT} = 5 V,	25°C	1.193	1.23	1.273	V
			$0.2 \text{ A} \le I_{\text{LOAD}} \le 1 \text{ A}$	Full range	1.180		1.286	
		TL2575HV-33	V _{IN} = 12 V, I _{LOAD} = 1 A			75		
		TL2575HV-05	V _{IN} = 12 V, I _{LOAD} = 1 A			77		
η	Efficiency	TL2575HV-12	V _{IN} = 15 V, I _{LOAD} = 1 A V _{IN} = 18 V, I _{LOAD} = 1 A	25°C		88		%
•	,	TL2575HV-15				88		
		TL2575HV-ADJ	$V_{IN} = 12 \text{ V}, V_{OUT} = 5 \text{ V},$ $I_{LOAD} = 1 \text{ A}$			77		
I _{IB}	Feedback bias curr	ent	V _{OLIT} = 5 V (ADJ version only)	25°C		50	100	nA
ΊΒ	r ceaback bias carr	Citt	VOUL = 2 4 (VD2 ACISIOLI OLILA)	Full range			500	ПА
f _o	Oscillator frequency	,(1)		25°C	47	52	58	kHz
'0	Oscillator frequency			Full range	42		63	KI IZ
V_{SAT}	Saturation voltage		I _{OUT} = 1 A ⁽²⁾	25°C		0.9	1.2	V
VSAI	Cataration voltage		1001 - 1 A	Full range			1.4	V
	Maximum duty cycl	e ⁽³⁾		25°C	93	98		%
la. Qui	Switch peak curren	₊ (1)(2)		25°C	1.7	2.8	3.6	Α
I _{CL}	CL Switch peak current A.A.			Full range	1.3		4	
IL	Output leakage cur	rent	$V_{IN} = 60^{(4)}$, Output = 0 V	25°C			2	mA
'L	Julput leanage cut		$V_{IN} = 60^{(4)}$, Output = -1 V	20.0		7.5	30	
I_Q	Quiescent current ⁽⁴)		25°C		5	10	mA
I_{STBY}	Standby quiescent	current	OFF $(\overline{ON}/OFF = 5 \text{ V})$	25°C		50	200	μΑ

⁽¹⁾ In the event of an output short or an overload condition, self-protection features lower the oscillator frequency to ~18 kHz and the minimum duty cycle from 5% to ~2%. The resulting output voltage drops to ~40% of its nominal value, causing the average power dissipated by the IC to lower.

⁽²⁾ Output is not connected to diode, inductor, or capacitor. Output is sourcing current.

⁽³⁾ FEEDBACK is disconnected from output and connected to 0 V.

⁽⁴⁾ To force the output transistor off, FEEDBACK is disconnected from output and connected to 12 V for the adjustable, 3.3-V, and 5-V versions and to 25 V for the 12-V and 15-V versions.



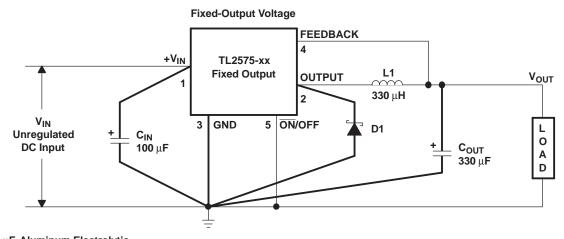
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TL2575HV Electrical Characteristics (continued)

PARAMETER		TEST CONDITIONS	_	TL2575HV			UNIT
	PARAWETER	TEST CONDITIONS	TJ	MIN	TYP	MAX	UNII
\/	ON/OFF high-level logic	OFF ()/ - 0.)/)	25°C	2.2	1.4		V
VIH	V _{IH} input voltage	OFF (V _{OUT} = 0 V)	Full range	2.4			V
\/	ON/OFF low lovel logic input voltage	ON (V _{OUT} = nominal voltage)	25°C		1.2	1	V
V _{IL}	ON/OFF low-level logic input voltage		Full range			0.8	V
I _{IH}	ON/OFF high-level input current	OFF (ON/OFF = 5 V)	25°C		12	30	μΑ
I _{IL}	ON/OFF low-level input current	ON $(\overline{ON}/OFF = 0 \text{ V})$	25'0		0	10	μΑ

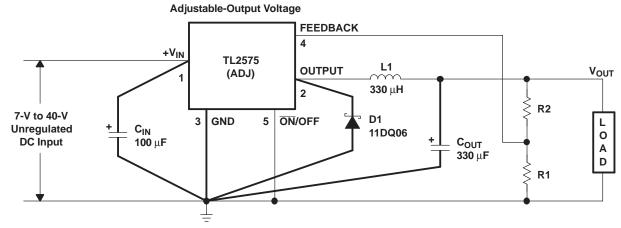
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TEST CIRCUITS



 C_{IN} = 100 μ F, Aluminum Electrolytic C_{OUT} = 330 μ F, Aluminum Electrolytic D1 = Schottky

L1 = 330 μH (for 5-V V_{IN} with 3.3-V V_{OUT}, use 100 $\mu\text{H})$



 $V_{OUT} = V_{REF}(1 + R2/R1) = 5 V$

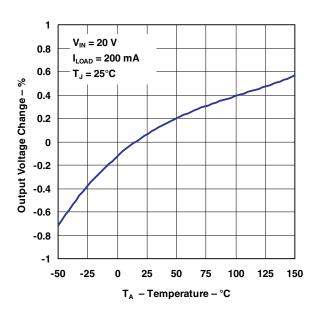
 V_{REF} = 1.23 V R1 = 2 k Ω R2 = 6.12 k Ω

A. Pin numbers are for the KTT (TO-263) package.

Figure 2. Test Circuits and Layout Guidelines



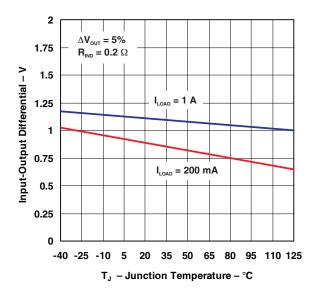
TYPICAL CHARACTERISTICS



1.4 $I_{LOAD} = 200 \text{ mA}$ 1.2 $T_J = 25^{\circ}C$ 1 Output Voltage Change – % 0.8 0.6 0.4 0.2 0 -0.2 -0.4 -0.6 0 10 20 30 40 50 60 V_{IN} - Input Voltage - V

Figure 3. Normalized Output Voltage





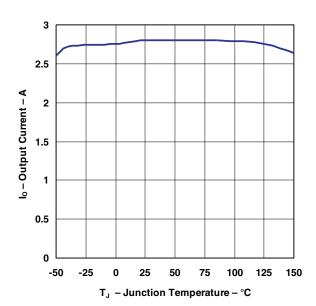
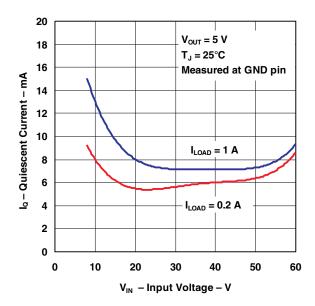


Figure 5. Dropout Voltage

Figure 6. Current Limit

TYPICAL CHARACTERISTICS (continued)



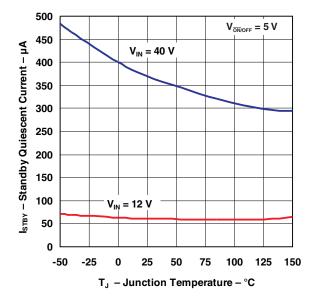
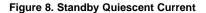
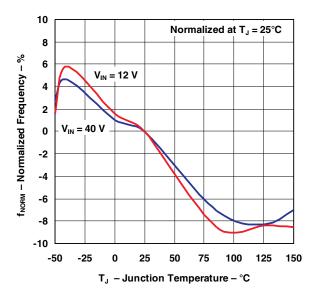


Figure 7. Quiescent Current





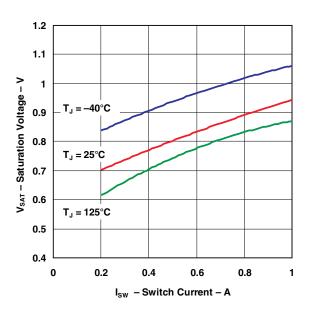
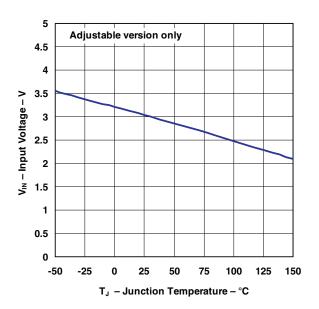


Figure 9. Oscillator Frequency

Figure 10. Switch Saturation Voltage



TYPICAL CHARACTERISTICS (continued)



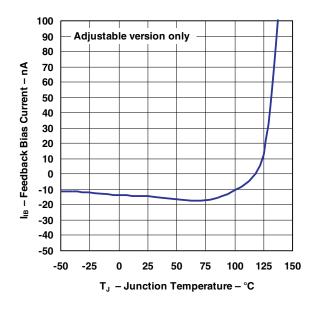
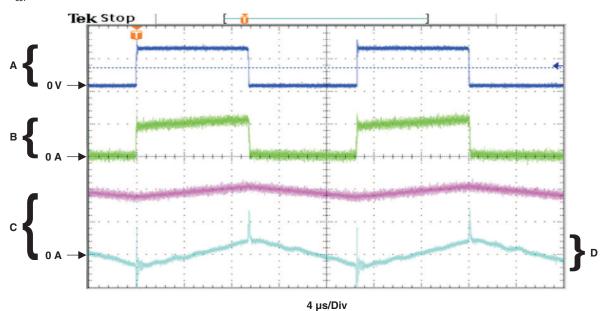


Figure 11. Minimum Operating Voltage

 $V_{\text{out}} = 5 \text{ V}$

Figure 12. FEEDBACK Current



- A. Output pin voltage, 10 V/Div
- B. Output pin current, 1 A/Div
- C. Inductor current, 0.5 A/Div
- D. Ouput ripple voltage, 20 mV/Div

Figure 13. Switching Waveforms

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TYPICAL CHARACTERISTICS (continued)

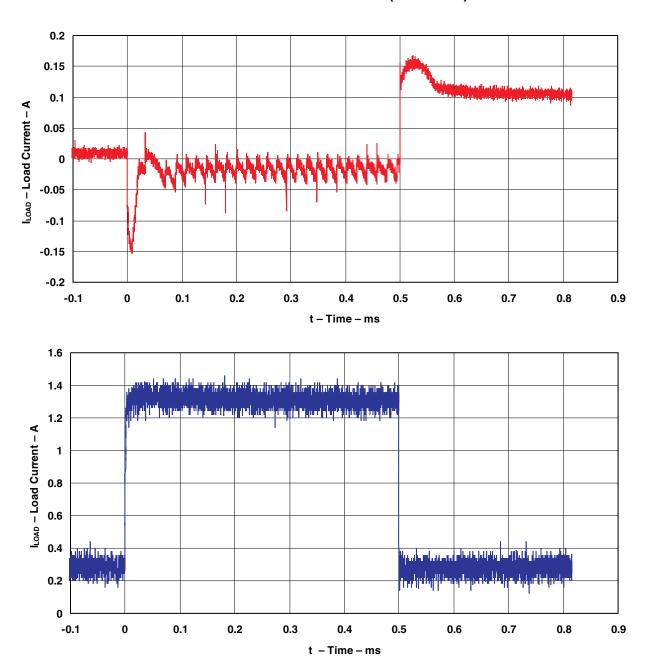


Figure 14. Load Transient Response

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APPLICATION INFORMATION

Input Capacitor (C_{IN})

For stability concerns, an input bypass capacitor (electrolytic, $C_{IN} \ge 47~\mu F$) needs to be located as close as possible to the regulator. For operating temperatures below $-25^{\circ}C$, C_{IN} may need to be larger in value. In addition, since most electrolytic capacitors have decreasing capacitances and increasing ESR as temperature drops, adding a ceramic or solid tantalum capacitor in parallel increases the stability in cold temperatures.

To extend the capacitor operating lifetime, the capacitor RMS ripple current rating should be:

 $I_{C,RMS} > 1.2(t_{on}/T)I_{LOAD}$ where $t_{on}/T = V_{OUT}/V_{IN} \text{ {buck regulator} } \text{ and } t_{on}/T = |V_{OUT}|/(|V_{OUT}| + V_{IN}) \text{ {buck-boost regulator} }$

Output Capacitor (C_{OUT})

For both loop stability and filtering of ripple voltage, an output capacitor also is required, again in close proximity to the regulator. For best performance, low-ESR aluminum electrolytics are recommended, although standard aluminum electrolytics may be adequate for some applications. Based on the following equation:

Output ripple voltage = (ESR of C_{OUT}) × (inductor ripple current)

Output ripple of 50 mV to 150 mV typically can be achieved with capacitor values of 220 μ F to 680 μ F. Larger C_{OUT} can reduce the ripple 20 mV to 50 mV peak to peak. To improve further on output ripple, paralleling of standard electrolytic capacitors may be used. Alternatively, higher-grade capacitors such as high frequency, low inductance, or low ESR can be used.

The following should be taken into account when selecting C_{OUT}:

- At cold temperatures, the ESR of the electrolytic capacitors can rise dramatically (typically 3× nominal value at -25°C). Because solid tantalum capacitors have significantly better ESR specifications at cold temperatures, they should be used at operating temperature lower than -25°C. As an alternative, tantalums also can be paralleled to aluminum electrolytics and should contribute 10% to 20% to the total capacitance.
- Low ESR for C_{OUT} is desirable for low output ripple. However, the ESR should be greater than 0.05 Ω to avoid the possibility of regulator instability. Hence, a sole tantalum capacitor used for C_{OUT} is most susceptible to this occurrence.
- The capacitor's ripple current rating of 52 kHz should be at least 50% higher than the peak-to-peak inductor ripple current.

Catch Diode

As with other external components, the catch diode should be placed close to the output to minimize unwanted noise. Schottky diodes have fast switching speeds and low forward voltage drops and, thus, offer the best performance, especially for switching regulators with low output voltages ($V_{OUT} < 5$ V). If a high-efficiency, fast-recovery, or ultra-fast-recovery diode is used in place of a Schottky, it should have a soft recovery (versus abrupt turn-off characteristics) to avoid the chance of causing instability and EMI. Standard 50-/60-Hz diodes, such as the 1N4001 or 1N5400 series, are not suitable.



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APPLICATION INFORMATION (continued)

Inductor

Proper inductor selection is key to the performance-switching power-supply designs. One important factor to consider is whether the regulator is used in continuous mode (inductor current flows continuously and never drops to zero) or in discontinuous mode (inductor current goes to zero during the normal switching cycle). Each mode has distinctively different operating characteristics and, therefore, can affect the regulator performance and requirements. In many applications, the continuous mode is the preferred mode of operation, since it offers greater output power with lower peak currents, and also can result in lower output ripple voltage. The advantages of continuous mode of operation come at the expense of a larger inductor required to keep inductor current continuous, especially at low output currents and/or high input voltages.

The TL2575 and TL2575HV can operate in either continuous or discontinuous mode. With heavy load currents, the inductor current flows continuously and the regulator operates in continuous mode. Under light load, the inductor fully discharges and the regulator is forced into the discontinuous mode of operation. For light loads (approximately 200 mA or less), this discontinuous mode of operation is perfectly acceptable and may be desirable solely to keep the inductor value and size small. Any buck regulator eventually operates in discontinuous mode when the load current is light enough.

The type of inductor chosen can have advantages and disadvantages. If high performance/quality is a concern, then more-expensive toroid core inductors are the best choice, as the magnetic flux is contained completely within the core, resulting in less EMI and noise in nearby sensitive circuits. Inexpensive bobbin core inductors, however, generate more EMI as the open core does not confine the flux within the core. Multiple switching regulators located in proximity to each other are particularly susceptible to mutual coupling of magnetic fluxes from each other's open cores. In these situations, closed magnetic structures (such as a toroid, pot core, or E-core) are more appropriate.

Regardless of the type and value of inductor used, the inductor never should carry more than its rated current. Doing so may cause the inductor to saturate, in which case the inductance quickly drops, and the inductor looks like a low-value resistor (from the dc resistance of the windings). As a result, switching current rises dramatically (until limited by the current-by-current limiting feature of the TL2575 and TL2575HV) and can result in overheating of the inductor and the IC itself. Note that different types of inductors have different saturation characteristics.

Output Voltage Ripple and Transients

As with any switching power supply, the output of the TL2575 and TL2575HV have a sawtooth ripple voltage at the switching frequency. Typically about 1% of the output voltage, this ripple is due mainly to the inductor sawtooth ripple current and the ESR of the output capacitor (see note on C_{OUT}). Furthermore, the output also may contain small voltage spikes at the peaks of the sawtooth waveform. This is due to the fast switching of the output switch and the parasitic inductance of C_{OUT} . These voltage spikes can be minimized through the use of low-inductance capacitors.

There are several ways to reduce the output ripple voltage: a larger inductor, a larger C_{OUT} , or both. Another method is to use a small LC filter (20 μ H and 100 μ F) at the output. This filter can reduce the output ripple voltage by a factor of 10 (see Figure 2).

Feedback Connection

For fixed-voltage options, FEEDBACK must be wired to V_{OUT} . For the adjustable version, FEEDBACK must be connected between the two programming resistors. Again, both of these resistors should be in close proximity to the regulator, and each should be less than 100 k Ω to minimize noise pickup.

ON/OFF Input

 $\overline{\text{ON}}/\text{OFF}$ should be grounded or be a low-level TTL voltage (typically <1.6 V) for normal operation. To shut down the TL2575 or TL2575HV and put it in standby mode, a high-level TTL or CMOS voltage should be supplied to this pin. $\overline{\text{ON}}/\text{OFF}$ should not be left open and safely can be pulled up to V_{IN} with or without a pullup resistor.

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APPLICATION INFORMATION (continued)

Grounding

The power and ground connections of the TL2575 and TL2575HV must be low impedance to help maintain output stability. For the 5-pin packages, both pin 3 and tab are ground, and either connection can be used as they are both part of the same lead frame. With the 16-pin package, all the ground pins (including signal and power grounds) should be soldered directly to wide PCB copper traces to ensure low-inductance connections and good thermal dissipation.

Layout Guidelines

With any switching regulator, circuit layout plays an important role in circuit performance. Wiring and parasitic inductances, as well as stray capacitances, are subjected to rapidly switching currents, which can result in unwanted voltage transients. To minimize inductance and ground loops, the length of the leads indicated by heavy lines should be minimized. Optimal results can be achieved by single-point grounding (see Figure 2) or by ground-plane construction. For the same reasons, the two programming resistors used in the adjustable version should be located as close as possible to the regulator to keep the sensitive feedback wiring short.



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BUCK REGULATOR DESIGN PROCEDURE

PROCEDURE (Fixed Output)	EXAMPLE (Fixed Output)
Known:	Known:
V _{OUT} = 3.3 V, 5 V, 12 V, or 15 V	V _{OUT} = 5 V
V _{IN(Max)} = Maximum input voltage	$V_{IN(Max)} = 20 \text{ V}$
I _{LOAD(Max)} = Maximum load current	$I_{LOAD(Max)} = 1 A$
1. Inductor Selection (L1)	1. Inductor Selection (L1)
A. From Figure 15 through Figure 18, select the appropriate inductor code based on the intersection of $V_{\text{IN}(\text{Max})}$ and $I_{\text{LOAD}(\text{Max})}$.	A. From Figure 16 (TL2575-05), the intersection of 20-V line and 1-A line gives an inductor code of L330.
B. From Table 2, choose the appropriate inductor based on the inductor code. Parts from three well-known inductor manufacturers are given. The inductor chosen should be rated for operation at 52-kHz and have a current rating of at least $1.15 \times I_{\text{LOAD}(\text{Max})}$ to allow for the ripple current. The actual peak current in L1 (in normal operation) can be calculated as follows:	B. L330 \rightarrow L1 = 330 μ H Choose from: 34042 (Schott) PE-52627 (Pulse Engineering) RL1952 (Renco)
$\begin{split} I_{L1(pk)} &= I_{LOAD(Max)} + (V_{IN} - V_{OUT}) \times t_{on}/2L1 \\ \text{Where } t_{on} &= V_{OUT}/V_{IN} \times (1/f_{osc}) \end{split}$	
2. Output Capacitor Selection (C _{OUT})	2. Output Capacitor Selection (C _{OUT})
A. The TL2575 control loop has a two-pole two-zero frequency response. The dominant pole-zero pair is established by C_{OUT} and L1. To meet stability requirements while maintaining an acceptable output ripple voltage ($V_{ripple}\approx 0.01\times V_{OUT}$), the recommended range for a standard aluminum electrolytic C_{OUT} is between 100 μF and 470 μF .	A. C _{OUT} = 100-μF to 470-μF, standard aluminum electrolytic
B. C_{OUT} should have a voltage rating of at least $1.5 \times V_{OUT}$. But if a low output ripple voltage is desired, choose capacitors with a higher-voltage ratings than the minimum required, due to their typically lower ESRs.	B. Although a C_{OUT} rated at 8 V is sufficient for $V_{OUT} = 5$ V, a higher-voltage capacitor is chosen for its typically lower ESR (and hence lower output ripple voltage) \rightarrow Capacitor voltage rating = 20 V.
3. Catch Diode Selection (D1) (see Table 1)	3. Catch Diode Selection (D1) (see Table 1)
A. In normal operation, the catch diode requires a current rating of at least $1.2 \times I_{LOAD(Max)}$. For the most robust design, D1 should be rated to handle a current equal to the TL2575 maximum switch peak current; this represents the worst-case scenario of a continuous short at V_{OUT} .	A. Pick a diode with 3-A rating.
B. The diode requires a reverse voltage rating of at least $1.25 \times V_{\text{IN(Max)}}$.	B. Pick 30-V rated Schottky diode (1N5821, MBR330, 31QD03, or SR303) or 100-V rated Fast Recovery diode (31DF1, MURD310, or HER302).
4. Input Capacitor (C _{IN})	4. Input Capacitor (C _{IN})
An aluminum electrolytic or tantalum capacitor is needed for input bypassing. Locate C_{IN} as close to the V_{IN} and GND pins as possible.	C_{IN} = 100 μF , 25 V, aluminum electrolytic

TL2575, TL2575HV

1-A SIMPLE STEP-DOWN SWITCHING VOLTAGE REGULATORS



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PROCEDURE (Adjustable Output)	EXAMPLE (Adjustable Output)
Known:	Known:
V _{OUT(Nom)}	V _{OUT} = 10 V
$V_{\text{IN(Max)}} = \text{Maximum input voltage}$	V _{IN(Max)} = 25 V
I _{LOAD(Max)} = Maximum load current	$I_{\text{LOAD}(Max)} = 1 \text{ A}$
1. Programming Output Voltage (Selecting R1 and R2)	1. Programming Output Voltage (Selecting R1 and R2)
Referring to Fig. 2, V _{OUT} is defined by:	Select R1 = 1 k Ω
$V_{OUT} = V_{REF} \left(1 + \frac{R2}{R1} \right)$ where $V_{REF} = 1.23 \text{ V}$	R2 = 1 (10/1.23 – 1) = 7.13 k Ω
Choose a value for R1 between 1 k Ω and 5 k Ω (use 1% metal-film	Select R2 = 7.15 k Ω (closest 1% value)
resistors for best temperature coefficient and stability over time).	
$R2 = R1 \left(\frac{V_{OUT}}{V_{DEE}} - 1 \right)$	
V _{REF}	
2. Inductor Selection (L1)	2. Inductor Selection (L1)
A. Calculate the "set" volts-second (E•T) across L1:	A. Calculate the "set" volts-second (E●T) across L1:
E-T = $(V_{IN} - V_{OUT}) \times t_{on}$	E•T = $(25 - 10) \times (10/25) \times (1000/52)$ [V•µs]
$E \bullet T = (V_{\text{IN}} - V_{\text{OUT}}) \times (V_{\text{OUT}}/V_{\text{IN}}) \times \{1000/f_{\text{osc}}(\text{in kHz})\} [V \bullet \mu s]$	E•T = 115 V•μs
NOTE: Along with I _{LOAD} , the "set" volts-second (E•T) constant	
establishes the minimum energy storage requirement for the inductor.	
B. Using Figure 19, select the appropriate inductor code based on	B. Using Figure 19, the intersection of 115 V•μs and 1 A
the intersection of E•T value and I _{LOAD(Max)} .	corresponds to an inductor code of H470.
C. From Table 2, choose the appropriate inductor based on the	C. H470 \rightarrow L1 = 470 μ F
inductor code. Parts from three well-known inductor manufacturers	Choose from:
are given. The inductor chosen should be rated for operation at 52-kHz and have a current rating of at least 1.15 x I _{LOAD(Max)} to	34048 (Schott)
allow for the ripple current. The actual peak current in L1 (in normal	PE-53118 (Pulse Engineering)
operation) can be calculated as follows:	RL1961 (Renco)
$I_{L1(pk)} = I_{LOAD(Max)} + (V_{IN} - V_{OUT}) \times t_{on}/2L1$	
Where $t_{on} = V_{OUT}/V_{IN} \times (1/f_{osc})$	
3. Output Capacitor Selection (C _{OUT})	3. Output Capacitor Selection (C _{OUT})
A. The TL2575 control loop has a two-pole two-zero frequency	A. C _{OUT} ≥ 7785 × 25/(10 × 470) [μ F]
response. The dominant pole-zero pair is established by C _{OUT} and	$C_{OUT} \ge 41.4 \mu\text{F}$
L1. To meet stability requirements, C _{OUT} must meet the following	To obtain an acceptable output voltage ripple $ ightarrow$
requirement: $C_{\text{OUT}} \geq 7758 \ \frac{V_{\text{IN(Max)}}}{V_{\text{OUT}} \bullet L1(\mu H)} (\mu F)$	$C_{OUT} = 220 \mu F$ electrolytic
V _{ουτ} • L1(μH) (μι)	
However, C _{OUT} may need to be several times larger than the	
calculated value above in order to achieve an acceptable output ripple voltage of $\sim 0.01 \times V_{OUT}$.	
B. C _{OUT} should have a voltage rating of at least 1.5 × V _{OUT} . But if a	
low output ripple voltage is desired, choose capacitors with a higher voltage ratings than the minimum required due to their typically	
lower ESRs.	
4. Catch Diode Selection (D1) (see Table 1)	4. Catch Diode Selection (D1) (see Table 1)
A. In normal operation, the catch diode requires a current rating of	A. Pick a diode with a 3-A rating.
at least 1.2 × I _{LOAD(Max)} . For the most robust design, D1 should be	
rated for a current equal to the TL2575 maximum switch peak current; this represents the worst-case scenario of a continuous	
short at V _{OUT} .	
B. The diode requires a reverse voltage rating of at least	B. Pick a 40-V rated Schottky diode (1N5822, MBR340, 31QD04, or
1.25 × V _{IN(Max)} .	SR304) or 100-V rated Fast Recovery diode (31DF1, MURD310, or
· · · ·	HER302)
5. Input Capacitor (C _{IN})	5. Input Capacitor (C _{IN})
An aluminum electrolytic or tantalum capacitor is needed for input	$C_{IN} = 100 \mu F$, 35 V, aluminum electrolytic
bypassing. Locate C _{IN} as close to V _{IN} and GND pins as possible.	

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Inductor Value Selection Guide for Continuous-Mode Operation

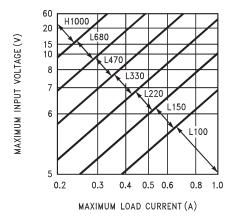


Figure 15. TL2575-33

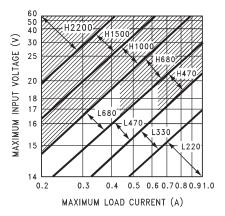


Figure 17. TL2575-12

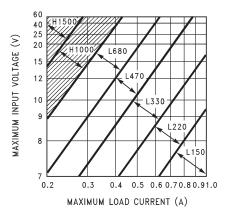


Figure 16. TL2575-50

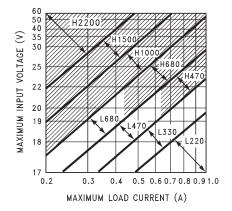


Figure 18. TL2575-15

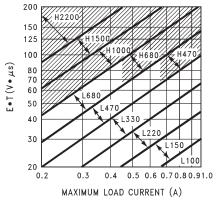


Figure 19. TL2575-ADJ



Table 1. Diode Selection Guide

V	SCHO	TTKY	FAST RECOVERY		
V _R	1A	3A	1A	3A	
20 V	1N5817 MBR120P SR102	1N5820 MBR320 SR302			
30 V	1N5818 MBR130P 11DQ03 SR103	1N5821 MBR330 31DQ03 SR303	The following diodes	The following diodes	
40 V	1N5819 MBR140P 11DQ04 SR104	IN5822 MBR340 31DQ04 SR304	are all rated to 100 V: 11DF1 MUR110 HER102	are all rated to 100 V: 31DF1 MURD310 HER302	
50 V	MBR150 11DQ05 SR105	MBR350 31DQ05 SR305			
60 V	MBR160 11DQ06 SR106	MBR360 31DQ06 SR306			

Table 2. Inductor Selection by Manufacturer's Part Number

INDUCTOR CODE	INDUCTOR VALUE (μH)	SCHOTT CORPORATION ⁽¹⁾	PULSE ENGINEERING ⁽²⁾	RENCO ELECTRONICS ⁽³⁾		
L100	100	67127000	PE-92108	RL2444		
L150	150	67127010	PE-53113	RL1954		
L220	220	67127020	PE-52626	RL1953		
L330	330	67127030	PE-52627	RL1952		
L470	470	67127040	PE-53114	RL1951		
L680	680	67127050	PE-52629	RL1950		
H150	150	67127060	PE-53115	RL2445		
H220	220	67127070	PE-53116	RL2446		
H330	330	67127080	PE-53117	RL2447		
H470	470	67127090	PE-53118	RL1961		
H680	680	67127100	PE-53119	RL1960		
H1000	1000	67127110	PE-53120	RL1959		
H1500	1500	67127120	PE-53121	RL1958		
H2200	2200	67127130	PE-53122	RL2448		

Schott Corporation, (612) 475-1173, 1000 Parkers Lake Rd., Wayzata, MN 55391
 Pulse Engineering, (619) 674-8100, P.O. Box 12236, San Diego, CA 92112

⁽³⁾ Renco Electronics Inc., (516) 586-5566, 60 Jeffryn Blvd. East, Deer Park, NY 11729





10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
TL2575-05IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575-05I	Sample
TL2575-05IKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575-05I	Sample
TL2575-05IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575-05I	Sample
TL2575-05IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-05IN	Sample
TL2575-12IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575-12l	Sample
TL2575-12IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575-12l	Sample
TL2575-12IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-12IN	Sample
TL2575-15IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575-15I	Sample
TL2575-15IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575-15I	Sample
TL2575-15IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-15IN	Sample
TL2575-33IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575-33I	Sample
TL2575-33IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575-33I	Sample
TL2575-33IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-33IN	Sample
TL2575-ADJIKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575ADJI	Sample
TL2575-ADJIKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL2575ADJI	Sampl
TL2575-ADJIKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575ADJI	Sampl
TL2575-ADJIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-ADJIN	Sampl



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Orderable Device	Status	Package Type	Package	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TL2575-ADJINE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575-ADJIN	Samples
TL2575HV-05IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-05I	Samples
TL2575HV-05IKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-05I	Samples
TL2575HV-05IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575HV-05I	Samples
TL2575HV-05IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575HV-05IN	Samples
TL2575HV-12IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-12I	Samples
TL2575HV-12IKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-12I	Samples
TL2575HV-12IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575HV-12I	Samples
TL2575HV-12IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575HV-12IN	Samples
TL2575HV-15IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-15I	Samples
TL2575HV-15IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575HV-15I	Samples
TL2575HV-15IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575HV-15IN	Samples
TL2575HV-33IKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-33I	Samples
TL2575HV-33IKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575HV-33I	Samples
TL2575HV-33IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575HV-33IN	Samples
TL2575HV-ADJIKTTR	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	2BHV-ADJI	Samples
TL2575HV-ADJIKV	ACTIVE	TO-220	KV	5	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TL2575HVADJI	Samples
TL2575HV-ADJIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TL2575HV-ADJIN	Samples

PACKAGE OPTION ADDENDUM



10-Jun-2014

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TL2575HV-05, TL2575HV-33:

Automotive: TL2575HV-05-Q1, TL2575HV-33-Q1



PACKAGE OPTION ADDENDUM

10-Jun-2014

TOM	re· c)ualified	Version	Definitions

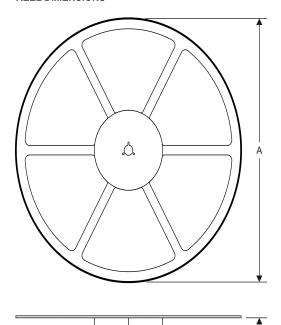
• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

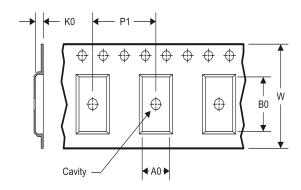
www.ti.com 22-Jun-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



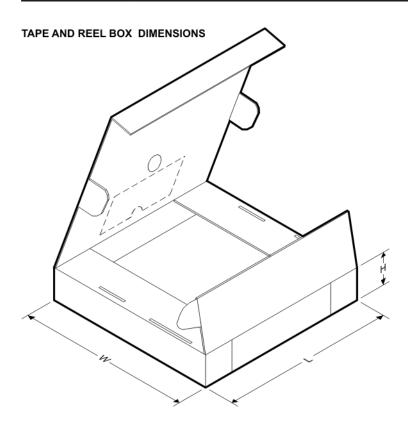
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL2575-05IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575-12IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575-15IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575-33IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575-ADJIKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575HV-05IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575HV-12IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575HV-15IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575HV-33IKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
TL2575HV-ADJIKTTR	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2

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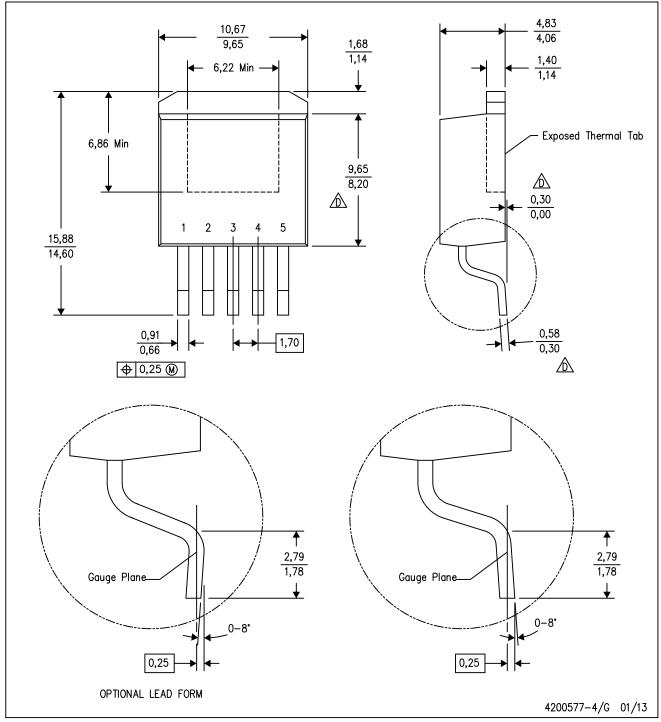


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL2575-05IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575-12IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575-15IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575-33IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575-ADJIKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575HV-05IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575HV-12IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575HV-15IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575HV-33IKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0
TL2575HV-ADJIKTTR	DDPAK/TO-263	KTT	5	500	340.0	340.0	38.0

KTT (R-PSFM-G5)

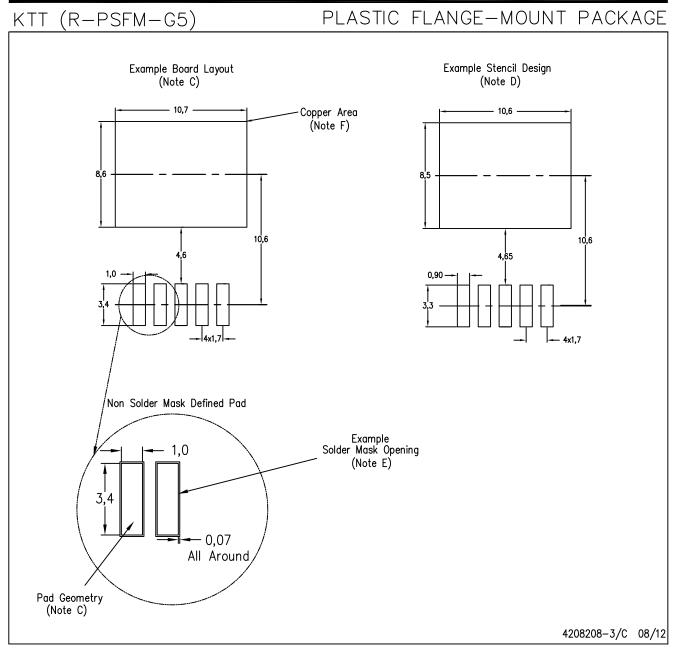
PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- Falls within JEDEC T0—263 variation BA, except minimum lead thickness, maximum seating height, and minimum body length.





NOTES: A.

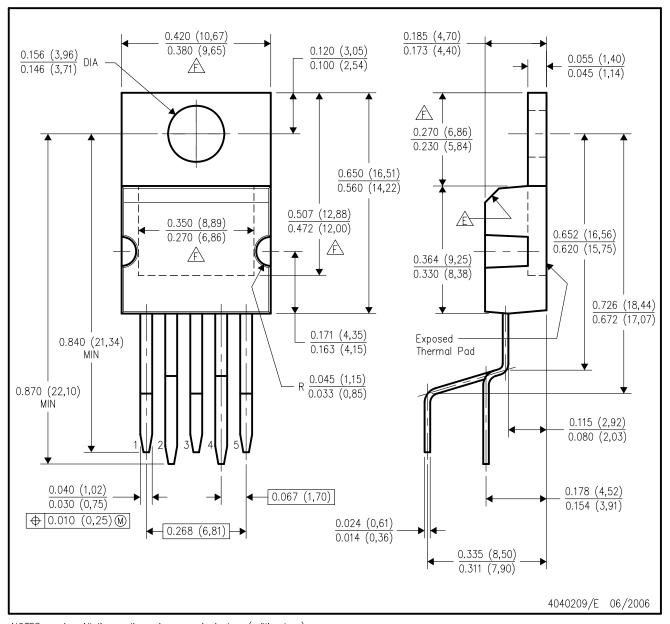
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.

 Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



KV (R-PZFM-T5)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. All lead dimensions apply before solder dip.
- D. The center lead is in electrical contact with the mounting tab.

The chamfer is optional.

Thermal pad contour optional within these dimensions.



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